



Product Change Notification: SYST-19EUFJ858

Date:

23-Dec-2025

Product Category:

Power Discrete Components

Notification Subject:

Lead Finish Change from Tin-Silver-Copper (SAC) to 100% Tin (Sn)

Affected CPNs:

[SYST-19EUFJ858_Affected_CPN_12232025.pdf](#)

[SYST-19EUFJ858_Affected_CPN_12232025.csv](#)

Notification Text:

SYST-19EUFJ858

Microchip has released a new Document for the Lead Finish Change from Tin-Silver-Copper (SAC) to 100% Tin (Sn) of devices. If you are using one of these devices please read the document located at [Lead Finish Change from Tin-Silver-Copper \(SAC\) to 100% Tin \(Sn\)](#).

Notification Status: Final

Description of Change:

Rev A

Initial release of document.

Impacts to Data Sheet: None

Change Implementation Status: Complete

Date Document Changes Effective: 23 Dec 2025

NOTE: Please be advised that this is a change to the document only the product has not been

changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachments:

Lead Finish Change from Tin-Silver-Copper (SAC) to 100% Tin (Sn)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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